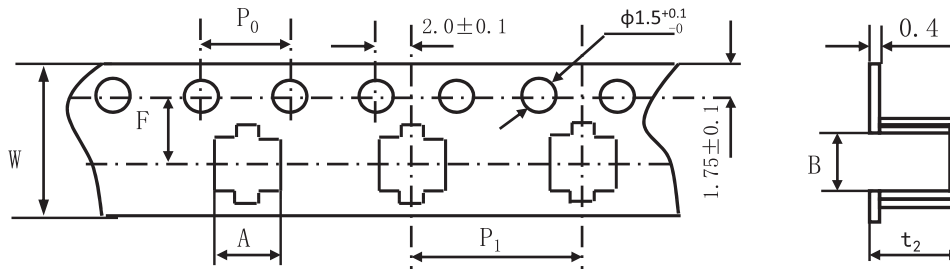


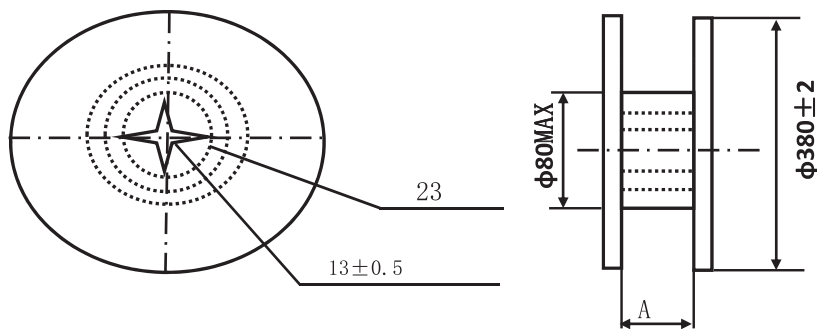
◆ V-CHIP编带 Carrier Taping

ΦD×L	W±0.3	A	B	P1±0.3	F±0.1	t ₂
Φ4×5.4	12	4.7	4.7	8	5.5	5.8
Φ5×5.4	12	6.0	6.0	12	5.5	5.8
Φ6.3×5.4	16	7.0	7.0	12	7.5	5.8
Φ6.3×7.7	16	7.0	7.0	12	7.5	8.3
Φ8×6.5	16	8.7	8.7	12	7.5	7.0
Φ8×10.2	24	8.7	8.7	16	11.5	11.0
Φ10×10.2	24	10.7	10.7	16	11.5	11.0



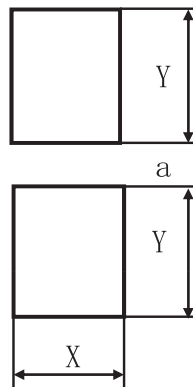
◆ V-CHIP编带包装 Reel

ΦD×L	卷装数量 Quantity/Reel	卷装数量 Quantity/Box	A
Φ4×5.4	2000PCS	20000PCS	14
Φ5×5.4	1000PCS	10000PCS	14
Φ6.3×5.4	1000PCS	10000PCS	18
Φ6.3×7.7	1000PCS	10000PCS	18
Φ8×6.5	1000PCS	10000PCS	18
Φ8×10.2	500PCS	5000PCS	26
Φ10×10.2	500PCS	5000PCS	26



◆ 表面安装推荐尺寸 Recommended Land Size

尺寸 Size	X	Y	a
Φ4	1.6	2.6	1.0
Φ5	1.6	3.0	1.4
Φ6.3	1.6	3.5	2.1
Φ8	2.5	3.5	3.0
Φ10	2.5	4.0	4.0



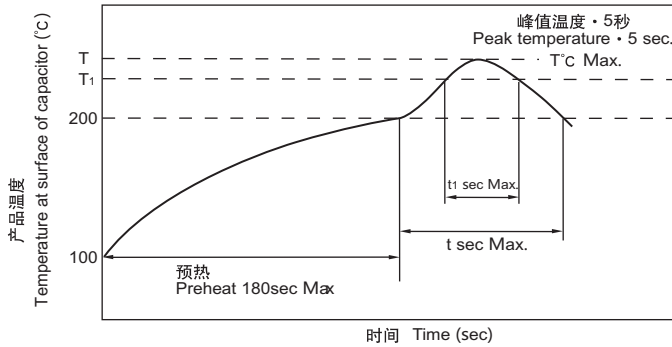
◆ V-CHIP产品额定纹波电流的频率系数 Frequency Coefficient of Rated Ripple Current

频率 Frequency	50Hz	120Hz	300Hz	1KHz	10KHz~
系数 Coefficient	0.70	1.00	1.17	1.36	1.50

◆无铅型回流焊允许条件 / LEAD FREE TYPE REFLOW SOLDERING CONDITION

●铝壳尺寸 $\phi 4 \sim \phi 10$ mm品 Size $\phi 4 \sim \phi 10$

- 1) 电容器表面温度在 $T^{\circ}\text{C}$ 以下。
Temperature at surface of capacitor shall not exceed $T^{\circ}\text{C}$.
- 2) 电容器表面温度在 200°C 以上的时间不能超过 t 秒, $T_1^{\circ}\text{C}$ 以上的时间不可超过 t_1 秒。
Period that temperature at surface of capacitor becomes more than 200°C and $T_1^{\circ}\text{C}$ shall not exceed t and t_1 seconds, respectively
- 3) 预热控制在 $100^{\circ}\text{C} \sim 200^{\circ}\text{C}$, 180秒以内。
Preheat shall be made at $100^{\circ}\text{C} \sim 200^{\circ}\text{C}$ and for maximum 180 seconds.



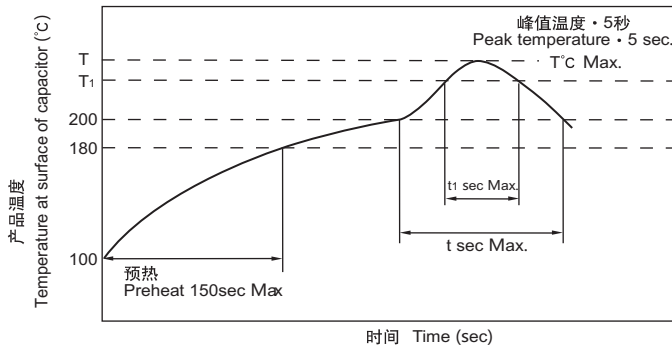
Series	Size	T(°C) 1	T ₁ (°C)	t(sec) 2	t ₁ (sec) 3	Reflow cycle
SGV TZV TXV	$\phi 4 \sim \phi 6.3$	250	230	90	40	1
TLV THV	$\phi 8$	240	230	90	30	1
TKV TGV	$\phi 10$	235	230	60	30	1
SJV SLV	$\phi 4 \sim \phi 6.3$	240	220	60	40	1
JGV	$\phi 4 \sim \phi 6.3$	260	217	-	60	2
JZV	$\phi 8, \phi 10$	250	217	-	60	2

- 1 峰值温度 Peak temperature
 - 2 超过 200°C 的时间 (MAX) Time more than 200°C
 - 3 超过 T_1 的时间 (MAX) Time more than T_1
- ※出现超过允许条件的情况, 请联系我们。
Please contact us if the condition is over the maximum.

◆无铅型回流焊允许条件 / LEAD FREE TYPE REFLOW SOLDERING CONDITION

●铝壳尺寸 $\phi 12.5 \sim \phi 18$ mm品 Size $\phi 12.5 \sim \phi 18$

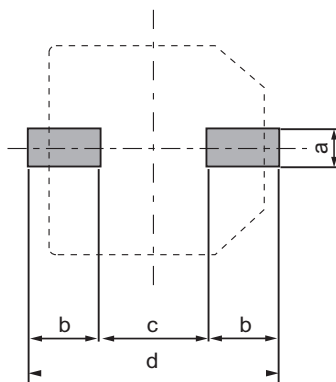
- 1) 电容器表面温度在 $T^{\circ}\text{C}$ 以下。 Temperature at surface of capacitor shall not exceed $T^{\circ}\text{C}$.
- 2) 电容器表面温度在 200°C 以上的时间不能超过 t 秒, $T_1^{\circ}\text{C}$ 以上的时间不可超过 t_1 秒。
Period that temperature at surface of capacitor becomes more than 200°C and $T_1^{\circ}\text{C}$ shall not exceed t and t_1 seconds, respectively.
- 3) 预热控制在 $100^{\circ}\text{C} \sim 180^{\circ}\text{C}$, 150秒以内。 Preheat shall be made at $100^{\circ}\text{C} \sim 180^{\circ}\text{C}$ and for maximum 150 seconds



Series	Size	T(°C) 1	T ₁ (°C)	t(sec) 2	t ₁ (sec) 3	Reflow cycle
SGV TLV TGV	$\phi 12.5 \sim \phi 18$	240	230	60	30	1

- 1 峰值温度 Peak temperature
 - 2 超过 200°C 的时间 (MAX) Time more than 200°C
 - 3 超过 T_1 的时间 (MAX) Time more than T_1
- ※出现超过允许条件的情况, 请联系我们。
Please contact us if the condition is over the maximum.

◆推荐焊盘尺寸 / RECOMMENDED LAND SIZE



尺寸 Size	a	bc	d	
$\phi 4$	1.6	2.6	1.0	6.2
$\phi 5$	1.6	3.0	1.4	7.4
$\phi 6.3$	1.6	3.5	2.1	9.1
$\phi 8 \times 6.5$	1.6	4.5	2.1	11.1
$\phi 8 \times 10.5$	2.2	4.1	3.0	11.2
$\phi 10 \times 10.5$	2.2	4.3	4.5	13.1
$\phi 12.5$	2.5	6.0	5.0	17
$\phi 16$	3	6.5	8.0	21
$\phi 18$	3	7.5	8.0	23